



SOIC-to-JEDEC TO Adapter

FEATURES

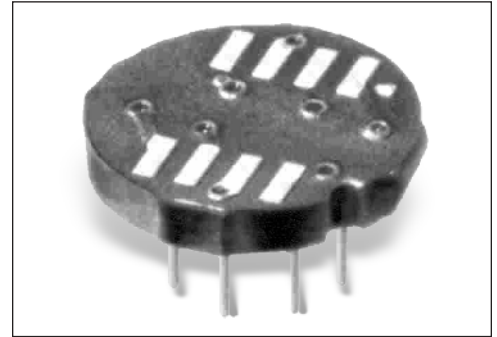
- 8-position SOIC footprint on the top and a circular, 8-pin JEDEC TO male pin footprint on the bottom. IC now available only in 8-position SOIC packages, can be readily mounted on boards having JEDEC TO thru-hole footprints without having to redesign the board.
- Consult factory for mounting of consigned chips.

GENERAL SPECIFICATIONS

- ADAPTER BOARD: FR-4, 0.062 [1.58] thick, with 1-oz. Cu traces both sides
- MALE PIN: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
- MALE PIN PLATING: 200 μ [5.08 μ] Sn/Pb 93/7 ASTM B579-73 over 100 μ [2.54 μ] Ni per SAE-AMS-QQ-N-290
- OPERATING TEMPERATURE: 221°F [105°C]

MOUNTING CONSIDERATIONS

- SUGGESTED PCB HOLE SIZE: 0.028 \pm 0.003 [0.71 \pm 0.08] dia.



CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE:** Aries reserves the right to change product general specifications without notice.

ORDERING INFORMATION

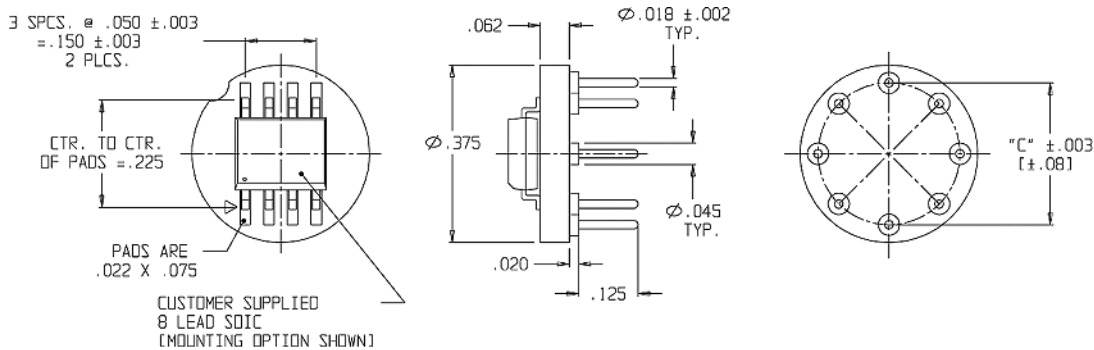
P/N	Dim "C"
1109814	0.200[5.08]
08-301296-10	0.300[7.62]
08-305479-10	0.270[6.85]

ALL DIMENSIONS: INCHES [MILLIMETERS]

ALL TOLERANCES: \pm 0.005 [0.13] UNLESS OTHERWISE SPECIFIED

DIP-to-TO ADAPTER ALSO AVAILABLE. CONSULT **DATA SHEET 18012**

CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS



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